

HERMETIC PACKAGE INFORMATION

PACKAGE TYPE	PACKAGE MATERIAL	DESCRIPTION	Package Dimensions mm (inch)		PACKAGE CODE	PACKAGE STYLE = Package Code + Lead Count	Lead Pitch mm (inches)	Theta JC °C/W	Theta JA °C/W	Lead Frame, Board Type	RAIL/BULK Quantity	Package Weight ⁽³⁾ (Grams)
			WIDTH	HEIGHT ⁽²⁾								
CERDIP	Ceramic	8-Lead CERDIP	7.62 (.300)	(.200) Maximum	J8	J8	2.54 (.100)	30	110	-	50	0.99
		14-Lead CERDIP		(.200) Maximum	J	J14	2.54 (.100)	25	95	-	25	2.09
		20-Lead CERDIP		(.200) Maximum	J	J20	2.54 (.100)	15	70	-	18	
Side-Brazed (Hermetic)	Ceramic	8-Lead SB	7.62 (.300)	5.71 (.225) Maximum	D8	D8	2.54 (.100)	30	100	-	35	
		14-Lead SB			D	D14	2.54 (.100)	25	85	-	25	
		16-Lead SB				D16	2.54 (.100)	25	80	-	25	
		18-Lead SB				D18	2.54 (.100)	20	75	-	20	
		20-Lead SB				D20	2.54 (.100)	15	70	-	20	
Flat Pack Glass Sealed	Ceramic	10-Lead Flatpak	7.62 (.300)	2.29 (.090) Maximum	W	W10	1.27 (.050)	40	170	-	20	0.25
		14-Lead Flatpak	7.62 (.300)	2.29 (.090) Maximum	W	W14	1.27 (.050)	40	160	-	20	0.45

Notes (1) Pin common to substrate

(2) Unless otherwise stated, Package height is nominal from seating/reference plane to top of package. Consult Package Drawing for details.

(3) Individual weight in grams, +/- 10%, of finished product with average die/device inside.

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			WIDTH	HEIGHT ⁽²⁾								
TO-3	Metal Can	2-Lead TO-3	12.70 (.500)	8.51 (.335)	K	K2	-	3	35	1 layer	20/Rail	12.8
TO-5	Metal Can	8-Lead TO-5	8.97 (.353)	5.84 (.230) Maximum	H	H8	-	40	150	-	10/Tray	0.96
		10-Lead TO-5				H10	-	38	150	-		1.04
TO-39	Metal Can	3-Lead TO-39	9.14 (.360)	4.7 (.185) Maximum	H	H3	-	15	150	Pin 3 ⁽¹⁾		0.97
		4-Lead TO-39				H4	-	14	150	Pin 4 ⁽¹⁾		
TO-46	Metal Can	2-Lead TO-46	5.44 (.214)	2.67 (.105) Maximum	H	H2	-	84	440	Pin 2 ⁽¹⁾		
		3-Lead TO-46				H3	-	80	440	Pin 3 ⁽¹⁾		0.29
		4-Lead TO-46				H4	-	76	440	Pin 4 ⁽¹⁾		
TO-52	Metal Can	3-Lead TO-52	5.44 (.214)	3.81 (.150) Maximum	E	E3	-	n/a	360	Pin 3 ⁽¹⁾		

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MARKING INK INFORMATION

1. MARKEM 7261 BLACK PHENOLIC OFFSET PRINT/ cured at 150degC for 3 hours (metal cans)
2. MARKEM 7224 WHITE EPOXY OFFSET PRINT/ cured at 150degC for 4 hours (cerpak and cerdip)
3. MARKEM 7254 GREY PHENOLIC OFFSET PRINT/ cured at 150degC for 4 hours (cerpack and cerdip)
4. TEKA PRINT AG TPC460 WHITE 1-component PAD PRINT/ cured at 150degC for 4 hours (cerpack and cerdip)

Please contact LTC for further details on specific device types.